

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>YEN-YU CHAO</td> <td>12/26/2013</td> </tr> <tr> <td>MING-WEI TIEN</td> <td>12/26/2013</td> </tr> <tr> <td>MING-CHANG WU</td> <td>12/26/2013</td> </tr> </tbody> </table>		Name	Execution Date	YEN-YU CHAO	12/26/2013	MING-WEI TIEN	12/26/2013	MING-CHANG WU	12/26/2013
Name	Execution Date								
YEN-YU CHAO	12/26/2013								
MING-WEI TIEN	12/26/2013								
MING-CHANG WU	12/26/2013								
RECEIVING PARTY DATA									
Name:	WISTRON CORPORATION								
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Internal Address:	HSICHIH DIST.								
City:	NEW TAIPEI CITY								
State/Country:	TAIWAN								
Postal Code:	22181								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14072488</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14072488				
Property Type	Number								
Application Number:	14072488								
CORRESPONDENCE DATA									
Fax Number:	(202)778-2201								
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ATTORNEY DOCKET NUMBER:	63084.005007								
NAME OF SUBMITTER:	WILLIAM J. ROSS								
Signature:	/William J. Ross/								

Date:	01/21/2014
	This document serves as an Oath/Declaration (37 CFR 1.63).
<p>Total Attachments: 4 source=63084-5007_Declarations#page1.tif source=63084-5007_Declarations#page2.tif source=63084-5007_Declarations#page3.tif source=63084-5007_Declarations#page4.tif</p>	

**COMBINED DECLARATION FOR UTILITY OR DESIGN PATENT APPLICATION,
ASSIGNMENT AND APPOINTMENT OF ATTORNEY (37 C.F.R. §1.63)**

(Earliest US or PCT application filing date must be on or after September 16, 2012)

As the below named inventor(s), I hereby declare that:

This declaration is directed to:

- The attached application,
 US or PCT International Application No. 14/072,488 filed on November 5, 2013

The TITLE of Invention is:

HEAT DISSIPATING DEVICE AND HEAT DISSIPATING FIN

I made or authorized the making of an application for the invention (design, if applicable) identified by the above Title.

I believe that I am the original inventor or an original joint inventor of the invention (design, if applicable) claimed in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under *Title 18, U.S. Code, §1001* by fine or imprisonment of not more than (5) years, or both.

I hereby state that I have reviewed and understand the contents of the above-identified application, including the claims; and I understand and am competent to execute this Declaration for Utility or Design Patent Application and Appointment of Attorney.

I am aware of and acknowledge the duty to disclose information which is material to the patentability of this application in accordance with *Title 37, Code of Federal Regulations, §1.56*

POWER OF ATTORNEY & CORRESPONDENCE ADDRESS

I hereby appoint the practitioners of **HUNTON & WILLIAMS LLP** associated with **CUSTOMER NUMBER 21967** as my attorneys or agents to prosecute this application and transact all business in the United States Patent and Trademark Office connected therewith. **Please direct all correspondence to the address associated with the above-noted Customer Number.**

ASSIGNMENT & APPLICANT INFORMATION

WHEREAS, I/We, whose full legal names, mailing addresses and residence addresses appear below hereinafter referred to as ASSIGNOR, have invented certain new and useful improvements in the application identified above (hereinafter referred to as THE INVENTION or design, if applicable) for which a patent is sought;

WHEREAS, Wistron Corporation, whose mailing address is 21F., No. 88, Sec. 1, Hsintai 5th Rd., Hsichih Dist., New Taipei City 22181, Taiwan (hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire right, title and interest in and to said application and the invention(s) and improvement(s) therein disclosed, for the United States of America, and any Letters Patent which may issue therefor in the United States and all divisions, continuations, reissues, renewals and/or extensions thereof.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, we, ASSIGNOR does hereby assign, sell, transfer and set over unto the ASSIGNEE the entire right, title and interest in and to said application and the invention(s) and improvement(s) therein disclosed, for the United States of America, and any Letters Patent which may issue therefor in the United States and all divisions, continuations, reissues, renewals and/or extensions thereof, said ASSIGNEE to have and to hold the interests herein assigned to the full ends of the terms of said Letters Patent and any and all divisions, continuations, reissues, renewals and/or extensions thereof, respectively, as fully and entirely as the same would have been held and enjoyed by the ASSIGNOR had this assignment not been made.

ACCORDINGLY, ASSIGNOR hereby acknowledges ASSIGNEE as sole APPLICANT for and to said INVENTION (design, if applicable) as defined under *Title 37, Code of Federal Regulations §§1.42 and 1.46*, and as defined and recognized under all available international conventions and treaties in respect of said INVENTION (design, if applicable).

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) or inventor certificate(s) in the United States, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said

INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION (design, if applicable) that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent referred to above to ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behalf; and for the use and behalf of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

<i>Full Legal Name of First or Sole Inventor (First and Middle + FAMILYNAME or SURNAME)</i> Yen-Yu CHAO			
<i>Residence Address - Street</i> 21F., No. 88, Sec. 1, Hsintai 5 th Rd., Hsichih Dist.		<i>Mailing Address - Street</i> 21F., No. 88, Sec. 1, Hsintai 5 th Rd., Hsichih Dist.	
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<i>SIGNATURE</i> Yen-Yu CHAO		<i>DATE</i> December 26, 2013	

See following pages for additional joint inventors.

<i>Full Legal Name of Next Inventor (First and Middle + FAMILY NAME or SURNAME)</i>			
<i>Residence Address - Street</i>		<i>Mailing Address - Street</i>	
<i>City</i>		<i>City</i>	
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<i>Full Legal Name of Next Inventor (First and Middle + FAMILY NAME or SURNAME)</i> Ming-Wei TIEN			
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<i>SIGNATURE</i> Tien, Ming-Wei		<i>DATE</i> December 26, 2013	

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<i>SIGNATURE</i> Ming-Chang Wu		<i>DATE</i> December 26, 2013	

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